AMENDMENT

IN THE CLAIMS:

1. (CURRENTLY AMENDED) A wafer rotating device comprising:

at least three rollers rotatably provided about axes arranged at parallel intervals ~~and~~, wherein each of the at least three rollers has a cylindrical surface which contacts ~~rotate over~~ a circumferential surface of a disk-shaped wafer;

a rotation drive mechanism that rotates and drives at least one of the rollers;

an interval adjustment mechanism capable of adjusting dimensions of the intervals of the rollers; and

a load control device that controls a load applied from the rollers to the wafer in a radial direction of the wafer when the wafer is clamped between the rollers,

wherein the wafer rotating device supports and rotates the wafer by a frictional force proportional to a contact load between the cylindrical surfaces of the rollers and the circumferential surface of the wafer.

2. (PREVIOUSLY PRESENTED) The wafer rotating device according to claim 1 wherein a load cell is provided in the interval adjustment mechanism that detects the load applied to the rollers along a direction of movement of the rollers, wherein the load control device controls the interval adjustment mechanism so that the load detected by the load cell is maintained constant.

3. (CURRENTLY AMENDED) The wafer rotating device according to claim 1 wherein the rollers are rotatably provided around the axes which are arranged roughly in a vertical direction, and the rollers include a flange section ~~and a circumferential surface~~, wherein the flange section has a diameter larger than the ~~circumferential~~ cylindrical surface of the rollers, and the flange section is provided below the ~~circumferential~~ cylindrical surface which clamps the wafer, and the flange section has an inclined surface in which an upper surface of the flange section gradually becomes lower moving towards an outside in a radial direction.

4. (PREVIOUSLY PRESENTED) The wafer rotating device according to claim 1 wherein an angle between two of the rollers adjacent to one of the rollers and on both sides of the one of the rollers is smaller than 180°.

5. (PREVIOUSLY PRESENTED) The wafer rotating device according to claim 4 wherein pairs of rollers are arranged at three or more locations at intervals in a circumferential direction of the wafer.

6. (CURRENTLY AMENDED) An edge flaw inspection device comprising:

a wafer rotating device including:

at least three rollers rotatably provided about axes arranged at parallel intervals ~~and~~, wherein each of the rollers has a cylindrical surface which contacts~~rotate over~~ a circumferential surface of a disk-shaped wafer,

a rotation drive mechanism that rotates and drives at least one of the rollers;

an interval adjustment mechanism capable of adjusting dimensions of the intervals of the rollers, and

a load control device ~~controls~~ that controls a load applied from the rollers to the wafer in a radial direction of the wafer when the wafer is clamped between the rollers, wherein the wafer rotating device supports and rotates the wafer by a frictional force proportional to a contact load between the cylindrical surfaces of the rollers and the circumferential surface of the wafer;

a light source that radiates light onto the circumferential surface of a wafer supported by the wafer rotating device; and

a light detector that detects light that has been radiated from the light source which is reflected on the circumferential surface of the wafer.

7. (NEW) The wafer rotating device as recited in claim 1 wherein the wafer includes a top surface and a bottom surface, and the wafer is rotated without any contact on the top surface and the bottom surface.

8. (NEW) The edge flaw inspection device as recited in claim 1 wherein the wafer includes a top surface and a bottom surface, and the wafer is rotated without any contact on the top surface and the bottom surface.